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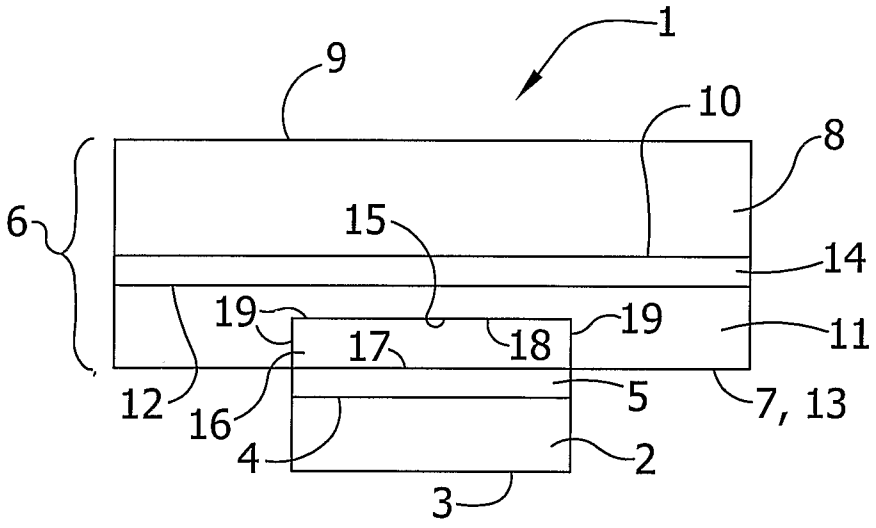
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(54) **Title:** THERMAL INTERFACE MATERIAL AND SOLDER PREFORMS



(57) **Abstract:** A solder preform (5,12) having multiple layers including a solder layer filled with additives interposed between two unfilled layers for improved wettability. A solder preform having a sphere which contains a solder material filled with additives, and an unfilled surface layer for improved wettability. Among the fillers are CTE modifying components and/or a thermal conductivity enhancement components.

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